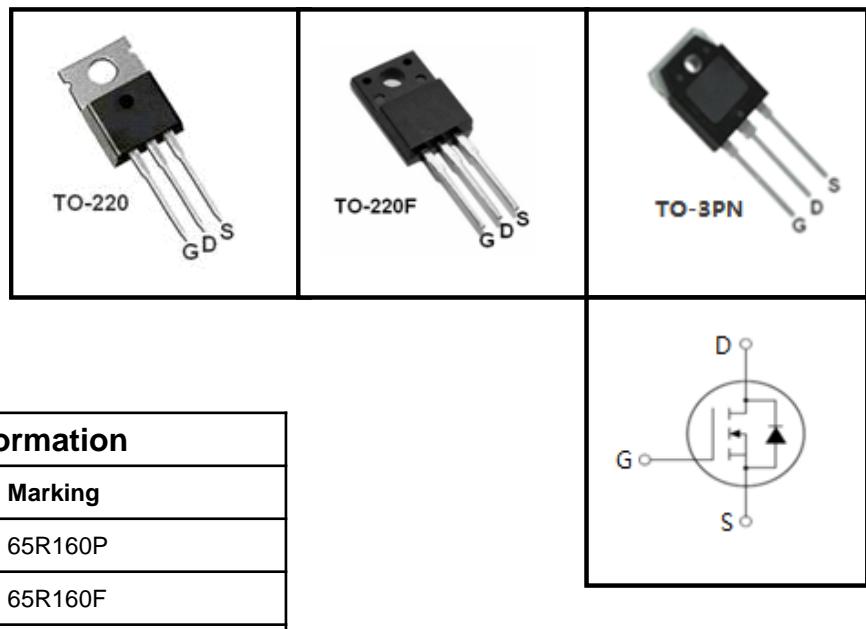


FEATURES

- Very low FOM $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- RoHS compliant

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information

Device	Package	Marking
SP65R160	TO-220	65R160P
SP65R160	TO-220F	65R160F
SP65R160	TO-3PN	65R160N

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value			Unit
		TO-220	TO-3PN	TO-220F	
Drain-Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}	650			V
Continuous Drain Current	I_D	20			A
Pulsed Drain Current (note1)	I_{DM}	60			A
Gate-Source Voltage	V_{GSS}	± 30			V
Single Pulse Avalanche Energy (note2)	E_{AS}	480			mJ
Avalanche Current (note1)	I_{AR}	4			A
Repetitive Avalanche Energy (note1)	E_{AR}	0.75			mJ
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	151	34		W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	$-55\text{--}+150$			$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Value			Unit
		TO-220	TO-3PN	TO-220F	
Thermal Resistance, Junction-to-Case	R_{thJC}	0.83	3.7	80	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62			

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1	μA
		$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 150^\circ\text{C}$	--	--	100	
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 30\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.5	--	4.0	V
Drain-Source On-Resistance (Note3)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$	--	0.14	0.16	Ω
Forward Transconductance (Note3)	g_{fs}	$V_{\text{DS}} = 10\text{V}, I_D = 10\text{A}$	--	18.8	--	S
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 50\text{V}, f = 1.0\text{MHz}$	--	2328	--	pF
Output Capacitance	C_{oss}		--	116	--	
Reverse Transfer Capacitance	C_{rss}		--	7	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 520\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$	--	46	--	nC
Gate-Source Charge	Q_{gs}		--	11	--	
Gate-Drain Charge	Q_{gd}		--	13	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 400\text{V}, I_D = 20\text{A}, R_G = 25\Omega$	--	43	--	ns
Turn-on Rise Time	t_r		--	14	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	150	--	
Turn-off Fall Time	t_f		--	7	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	20.6	A
Pulsed Diode Forward Current	I_{SM}		--	--	70	
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 20\text{A}, V_{\text{GS}} = 0\text{V}$	--	0.95	1.2	V
Reverse Recovery Time	t_{rr}	$V_R = 520\text{V}, I_F = I_S, dI_F/dt = 100\text{A}/\mu\text{s}$	--	460	--	ns
Reverse Recovery Charge	Q_{rr}		--	8.2	--	
Peak Reverse Recovery Current	I_{rrm}		--	35	--	A

Notes

1. Repetitive Rating: Pulse Width limited by maximum junction temperature
2. $I_{AS} = 4\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

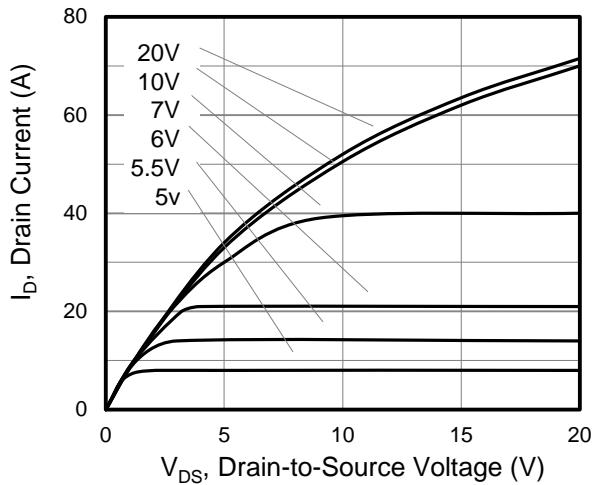


Figure 2. Transfer Characteristics

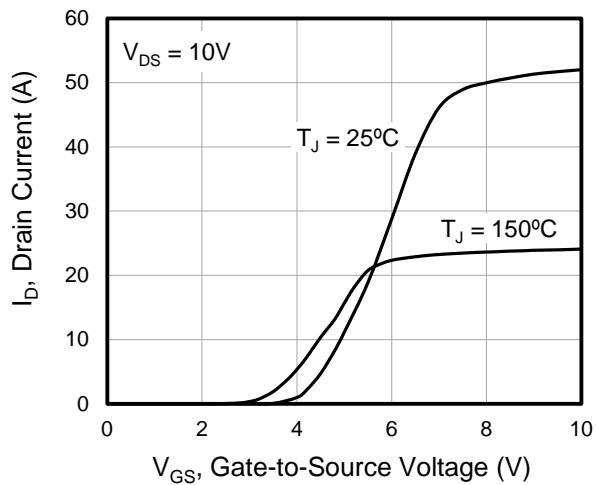


Figure 3. On-Resistance vs. Drain Current

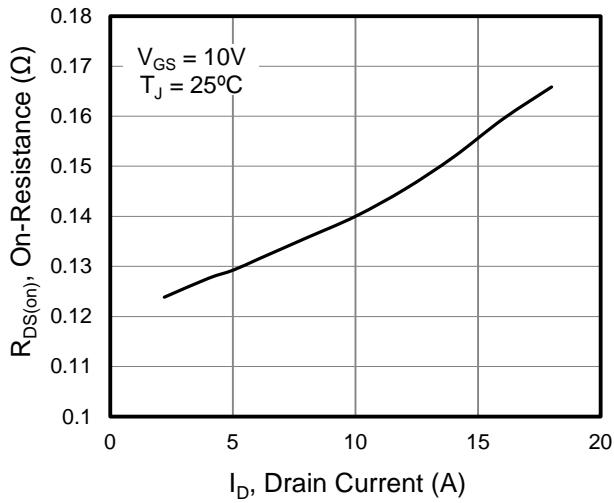


Figure 4. Capacitance

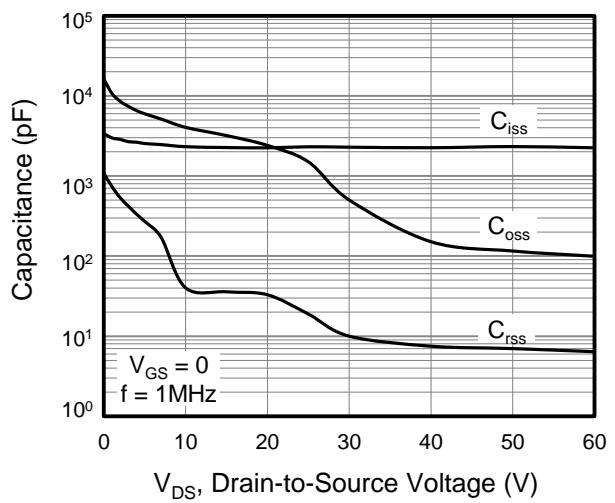


Figure 5. Gate Charge

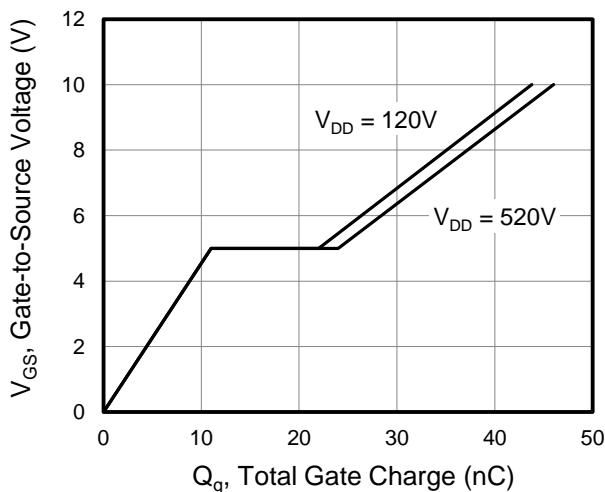
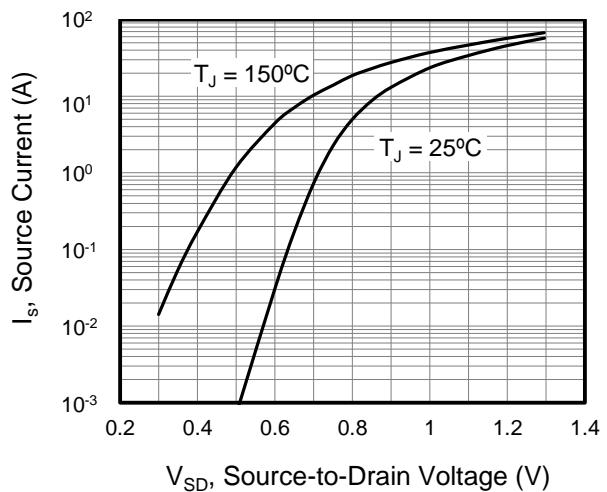
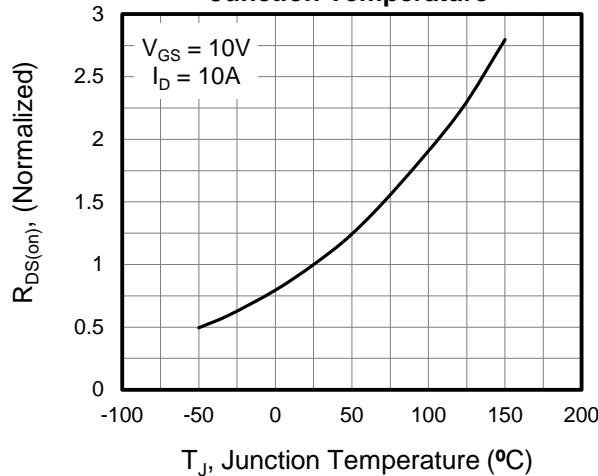


Figure 6. Body Diode Forward Voltage

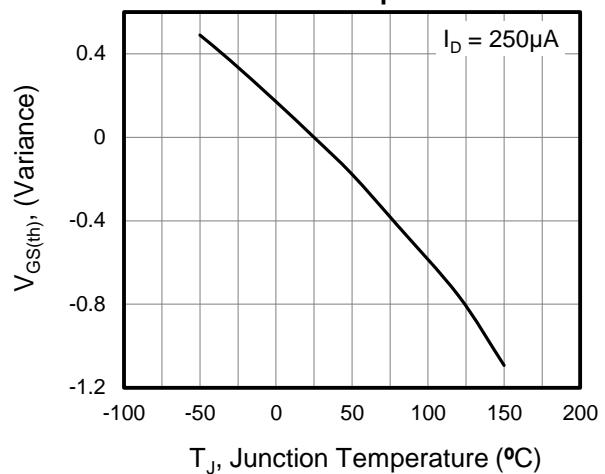


Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

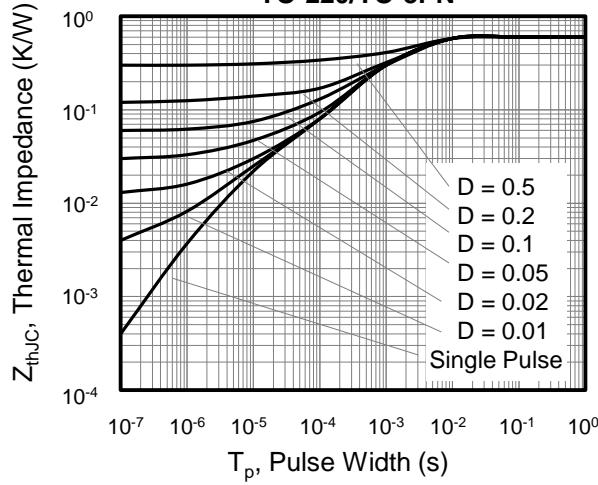
**Figure 7. On-Resistance vs.
Junction Temperature**



**Figure 8. Threshold Voltage vs.
Junction Temperature**



**Figure 9. Transient Thermal Impedance
TO-220/TO-3PN**



**Figure 10. Transient Thermal Impedance
TO-220F**

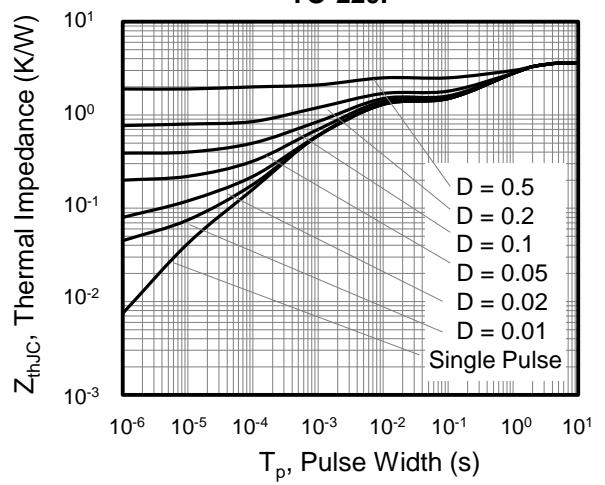
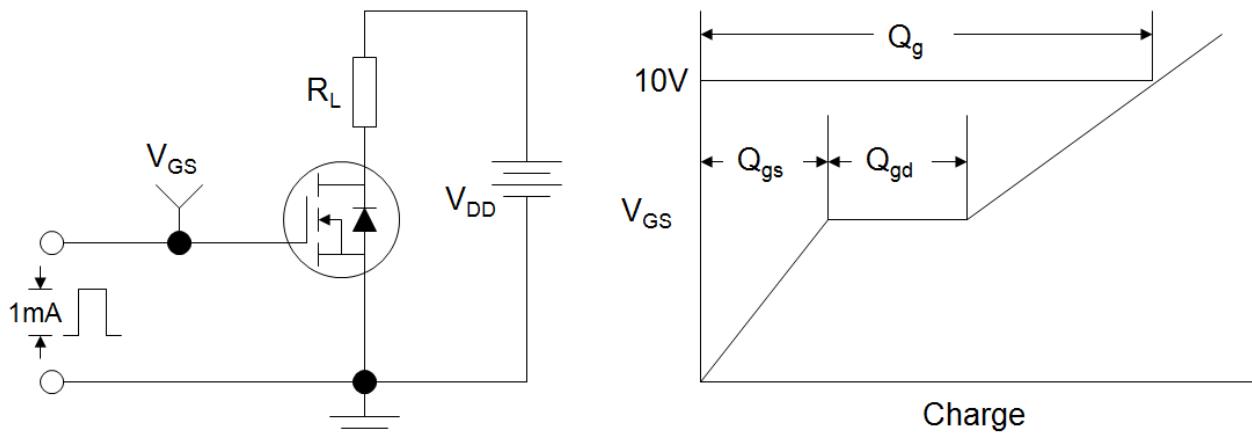
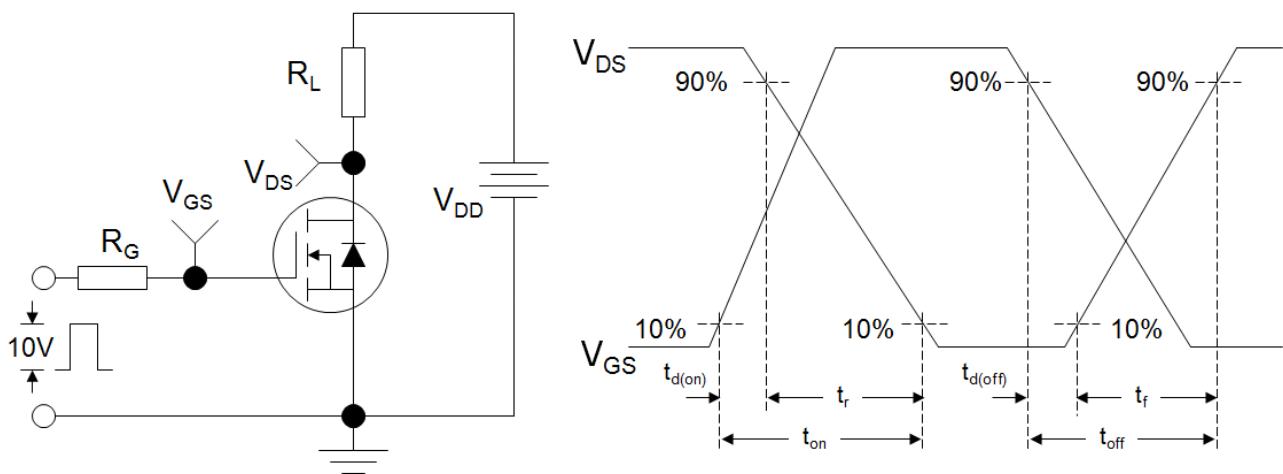
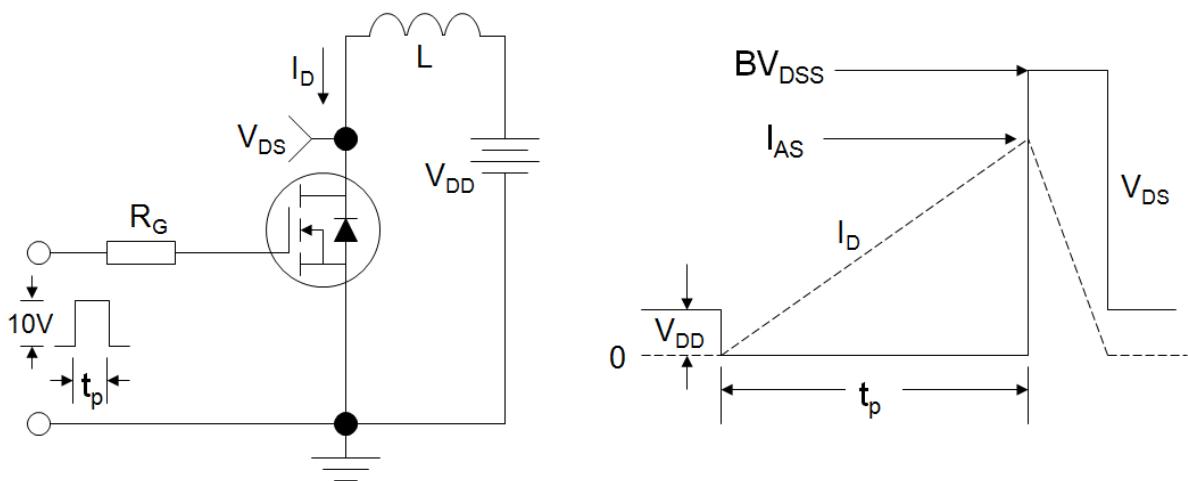
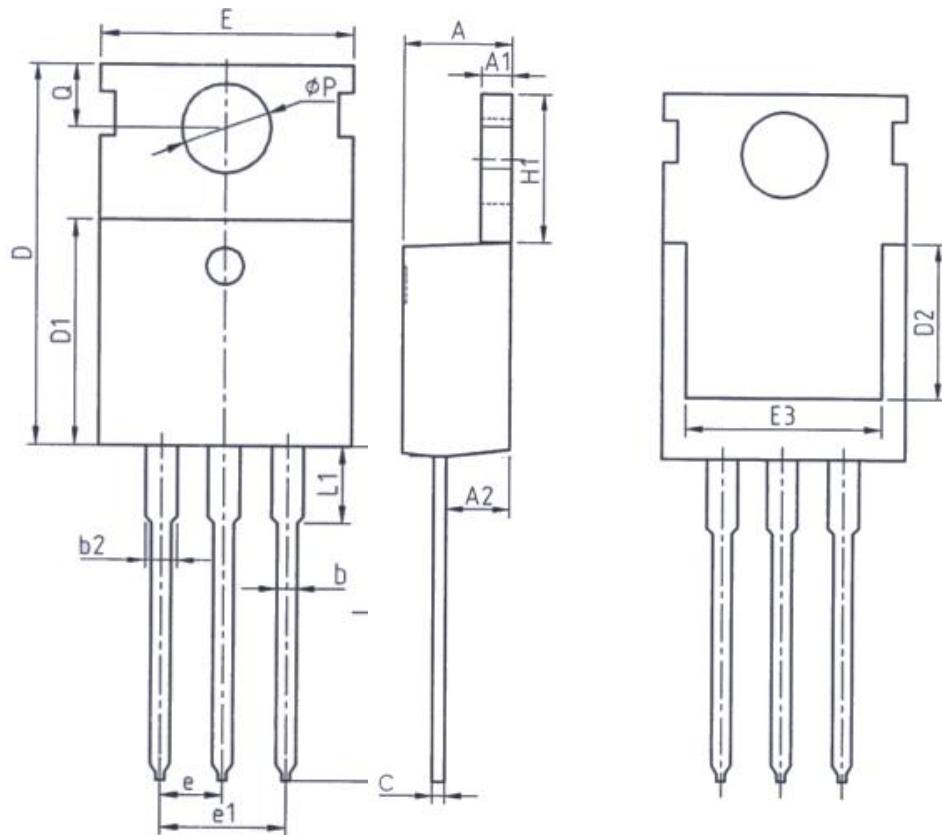


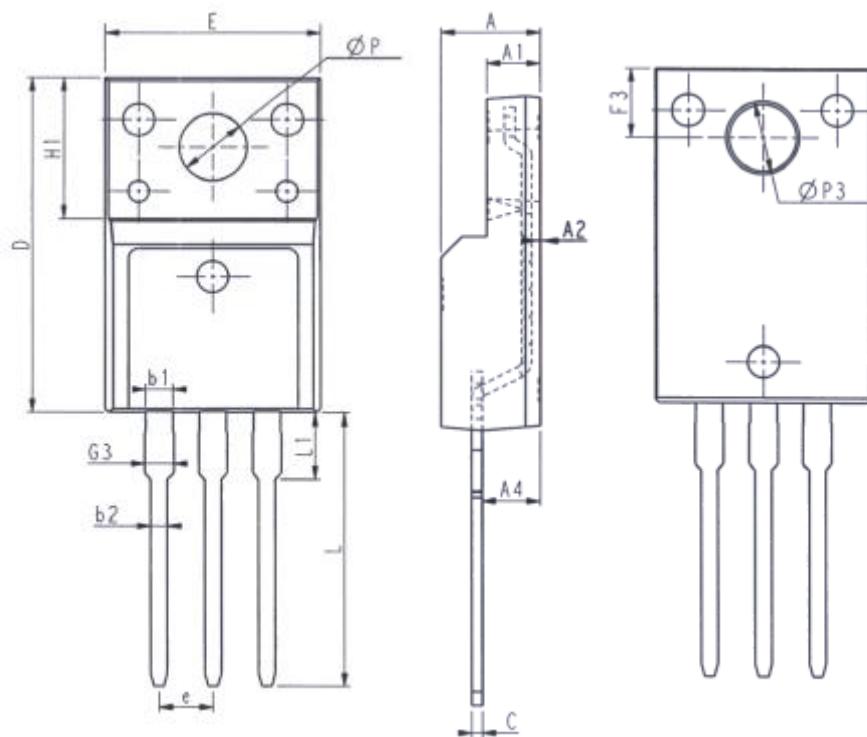
Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform


TO-220


Unit: mm		
Symbol	Min.	Max.
A	4.37	4.77
A1	1.25	1.45
A2	2.20	2.60
b	0.70	0.95
b2	1.17	1.47
c	0.40	0.65
D	15.10	16.10
D1	8.80	9.40
D2	5.50	-

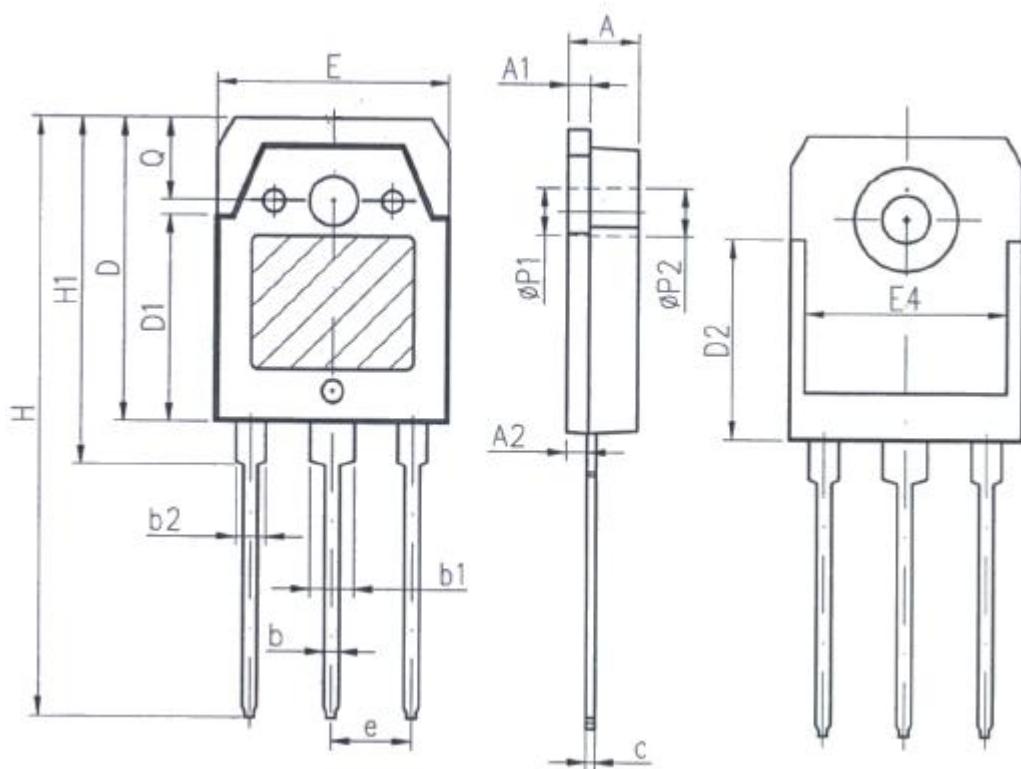
Unit: mm		
Symbol	Min.	Max.
E	9.70	10.30
E3	7.00	-
e	2.54BSC	
e1	5.08BSC	
H1	6.25	6.85
L	12.75	13.80
L1	-	3.40
P	3.40	3.80
Q	2.60	3.00

TO-220F



Unit: mm		
Symbol	Min.	Max.
E	9.96	10.36
A	4.50	4.90
A1	2.34	2.74
A2	0.30	0.60
A4	2.56	2.96
c	0.40	0.65
D	15.57	16.17
H1	6.70REF	
e	2.54BSC	

Unit: mm		
Symbol	Min.	Max.
L	12.68	13.28
L1	2.93	3.13
P	3.03	3.38
P3	3.15	3.65
F3	3.15	3.45
G3	1.25	1.55
b1	1.18	1.43
b2	0.70	0.95

TO-3PN


Unit : mm		
Symbol	Min.	Max.
A	4.6	5
A1	1.4	1.65
A2	1.18	1.58
b	0.8	1.2
b1	2.8	3.2
b2	1.8	2.2
c	0.5	0.75
D	19.6	20.2
D1	13.55	14.25
D2	12.9REF	
E	15.35	15.85
E4	12.6	-
e	5.45TYP	
H	40.1	40.9
H1	23.15	23.65
P1	3.2REF	
P2	3.5REF	